

42390.P9556X



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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*2-11-02*  
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**In re Application of:**

Ma, et al.

**Serial No.:** 09/640,961

**Filed:** August 16, 2000

**For:** DIRECT BUILD-UP LAYER ON AN  
ENCAPSULATED DIE PACKAGE

**Examiner:** S. Clark

**Group Art Unit:** 2815

**Attorney Docket No.:** 42390.P9556

CERTIFICATE OF MAILING

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SUPPLEMENTAL PRELIMINARY AMENDMENT

Hon. Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

Applicants respectfully request that the Examiner enter the following amendment:

IN THE SPECIFICATION:

Page 1, between lines 3 and 4, please insert:

~ This is a continuation-in-part of Application No. [09/516,652] 09/438,221 filed

November 12, 1999, now U.S. Patent No. 6,271,469, issued August 7, 2001. ~